DIGITRON SEMICONDUCTORS

3N211-3N213

DUAL-GATE VHF AMPLIFIER N-CHANNEL - DEPLETION

MAXIMUM RATINGS

| Rating | Symbol | 3N211 3N212 | 3N213 | Unit |
|---|--------------------------------------|----------------|----------|---------------|
| Drain Source Voltage | V _{DS} | 27 35 | | Vdc |
| Drain Gate Voltage | V _{DG1} V _{DG2} | 35 35 | 40 40 | Vdc |
| Drain Current | I _D | 50 | | mAdc |
| Gate Current | I_{G1} I_{G2} | ±10 ±10 | | mAdc |
| Total Device Dissipation @ T _A = 25°C Derate above 25°C | P _D | 360 2.4 | | mW mW/°C |
| Total Device Dissipation @ T _c = 25°C Derate above 25°C | P _D | 1.2 8.0 | | Watt mW/°C |
| Lead Temperature, 1/16" from Seated Surface for 10 seconds | TL | 300 | | °C |
| Junction Temperature Range | Tı | -65 to +175 | | °C |
| Storage Temperature Range | T _{stg} | -65 to +175 | | °C |

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}$ unless otherwise noted)

| Characteristics | | Symbol | Min | Мах | Unit | |
|---|-----------------------|-----------------------|--------------|--------------|--------------|--|
| OFF CHARACTERISTICS | | | | | | |
| Drain Source Breakdown Voltage ⁽¹⁾ ($I_D = 10 \ \mu Adc, V_{G1S} = V_{G2S} = -4.0 \ Vdc$) | 3N211, 3N212 3N213 | V _{(BR)DSX} | 25 30 | - | Vdc | |
| Instantaneous Drain Source Breakdown Voltage ($I_D = 10 \ \mu Adc, V_{G1S} = V_{G2S} = -4.0 \ Vdc$) | 3N211, 3N212 3N213 | V _{(BR)DSX} | 27 35 | - | Vdc | |
| Gate 1 – Source Breakdown Voltage ⁽²⁾ ($I_{G1} = \pm 10 \text{ mAdc}, V_{G2S} = V_{DS} = 0$) | | V _{(BR)G1S0} | ±6.0 | - | Vdc | |
| Gate 2 – Source Breakdown Voltage ⁽²⁾ ($I_{G2} = \pm 10 \text{ mAdc}, V_{G1S} = V_{DS} = 0$) | | V _{(BR)G2SO} | ±6.0 | - | Vdc | |
| Gate 1 Leakage Current $(V_{G1S} = \pm 5.0 \text{ Vdc}, V_{G2S} = V_{DS} = 0)$ $(V_{G1S} = -5.0 \text{ Vdc}, V_{G2S} = V_{DS} = 0, T_A = 150^{\circ}\text{C})$ | | I _{G1SS} | - | ±10 -10 | nAdc µAdc | |
| | | I _{G2SS} | - | ±10 -10 | nAdc µAdc | |
| Gate 1 to Source Cutoff Voltage $(V_{DS} = 15 \text{ Vdc}, V_{G2S} = 4.0 \text{ Vdc}, I_D = 20 \mu \text{ Adc})$ | 3N211, 3N213 3N212 | $V_{G1S(off)}$ | -0.5 -0.5 | -5.5 -4.0 | Vdc | |
| Gate 2 Source to Cutoff Voltage $(V_{DS} = 15 \text{ Vdc}, V_{G1S} = 0, I_D = 20 \mu \text{Adc})$ | 3N211 3N212, 3N213 | $V_{G2S(off)}$ | -0.2 -0.2 | -2.5 -4.0 | Vdc | |
| ON CHARACTERISTICS | | | | | | |
| Zero Gate Voltage Drain Current $^{(3)}$ (V _{DS} = 15 Vdc, V _{G1S} = 0, V _{G2S} = 4.0 Vdc) | | \mathbf{I}_{DSS} | 6.0 | 40 | mAdc | |
| SMALL SIGNAL CHARACTERISTICS | | | | | | |
| Forward Transfer Admittance $^{(4)}$ (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, V _{G1S} = 0, f = 1.0 kHz) | 3N211, 3N212 3N213 | yfs | 17 15 | 40 35 | mmhos | |
| Reverse Transfer Capacitance $(V_{DS} = 15 \text{ Vdc}, V_{G2S} = 4.0 \text{ Vdc}, I_D = 1.0 \text{ mAdc}, f = 1.0 \text{ MHz})$ | | C _{rss} | 0.005 | 0.05 | pF | |
| FUNCTIONAL CHARACTERISTICS | | | | | | |
| Noise Figure $(V_{DD} = 18 \text{ Vdc}, V_{GG} = 7.0 \text{ Vdc}, f = 200 \text{ MHz})$ $(V_{DD} = 24 \text{ Vdc}, V_{GG} = 6.0 \text{ Vdc}, f = 45 \text{ MHz})$ | 3N211 3N211, 3N213 | NF | - | 3.5 4.0 | dB | |

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DUAL-GATE VHF AMPLIFIER N-CHANNEL - DEPLETION

ELECTRICAL CHARACTERISTICS (T_A = 25° unless otherwise noted)

| Characteristics | | Symbol | Min | Max | Unit |
|---|--------------|---------------------|-----|------|------|
| FUNCTIONAL CHARACTERISTICS (con't) | | | | | |
| Common Source Power Gain | | G _{ps} | | | |
| $(V_{DD} = 18 \text{ Vdc}, V_{GG} = 7.0 \text{ Vdc}, f = 200 \text{ MHz})$ | 3N211 | | 24 | 35 | |
| $(V_{DD} = 24 \text{ Vdc}, V_{GG} = 6.0 \text{ Vdc}, f = 45 \text{ MHz})$ | 3N211 | | 29 | 37 | dB |
| $(V_{DD} = 24 \text{ Vdc}, V_{GG} = 6.0 \text{ Vdc}, f = 45 \text{ MHz})$ | 3N213 | | 27 | 35 | |
| $(V_{DD} = 18 \text{ Vdc}, f_{LO} = 245 \text{ MHz}, f_{RF} = 200 \text{ MHz})$ | 3N212 | Gc ⁽⁶⁾ | 21 | 28 | |
| Bandwidth | | BW | | | |
| $(V_{DD} = 18 \text{ Vdc}, V_{GG} = 7.0 \text{ Vdc}, f = 200 \text{ MHz})$ | 3N211 | | 5.0 | 12 | MU- |
| $(V_{DD} = 18 \text{ Vdc}, f_{LO} = 245 \text{ MHz}, f_{RF} = 200 \text{ MHz})$ | 3N212 | | 4.0 | 7.0 | MUL |
| $(V_{DD} = 24 \text{ Vdc}, V_{GG} = 6.0 \text{ Vdc}, f = 45 \text{ MHz})$ | 3N211, 3N213 | | 3.5 | 6.0 | |
| Gain Control Gate Supply Voltage ⁽⁵⁾ | | V _{gg(gc)} | | | |
| $(V_{DD} = 18 \text{ Vdc}, \Delta \text{ Gps} = -30 \text{ dB}, \text{ f} = 200 \text{ MHz})$ | 3N211 | | - | -2.0 | Vdc |
| $(V_{DD} = 24 \text{ Vdc}, \Delta \text{ Gps} = -30 \text{ dB}, \text{ f} = 45 \text{ MHz})$ | 3N211, 3N213 | | - | ±1.0 | |

Measured after five seconds of applied voltage. (1)

(2) All gate breakdown voltages are measured while the device is conducting rated gate current. This ensures that the gate voltage limiting network is functioning properly.

Pulse test: Pulse width = $300\mu s$, Duty cycle $\leq 2.0\%$. (3)

This parameter must be measured with bias voltages applied for less than 5 seconds to avoid overheating. The signal is applied to gate 1 with gate 2 at ac ground. (4)

 Δ Gps is defined as the change in G_{ps} from the value at V_{GG} = 7.0 Volts (3N211) and V_{GG} = 6.0 Volts (3N213). Power Gain Conversion. Amplitude at input from local oscillator is adjusted for maximum G_c. (5) (6)







| Dim | Inches | | Millimeters | | |
|-----|-----------|--------|-------------|-------|--|
| | Min | Max | Min | Max | |
| Α | - | 0.230 | - | 5.840 | |
| В | - | 0.195 | - | 4.950 | |
| С | - | 0.210 | - | 5.330 | |
| D | - | 0.021 | - | 0.530 | |
| Е | - | 0.030 | - | 0.760 | |
| F | - | 0.019 | - | 0.480 | |
| G | 0.100 BSC | | 2.540 BSC | | |
| Н | - | 0.046 | - | 1.170 | |
| J | - | 0.0480 | - | 1.220 | |
| K | 0.500 | - | 12.700 | - | |
| L | 0.250 | - | 6.350 | - | |
| М | 45°C BSC | | 45°C BSC | | |
| N | 0.050 BSC | | 1.270 BSC | | |
| Р | - | 0.050 | - | 1.270 | |

Available Non-RoHS (standard) or RoHS compliant (add PBF suffix). Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.